



## Material Content Data Sheet



<b>Sales Product Name</b>	BTS133	<b>Issued</b>	03. May 2021
<b>MA#</b>	MA001017948		
<b>Package</b>	PG-TO220-3-1	<b>Weight*</b>	2020.77 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	5.075	0.25	0.25	2511	2511
chip_2	inorganic material	silicon	7440-21-3	0.454	0.02	0.02	225	225
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		121	
	non noble metal	iron	7439-89-6	0.816	0.04		404	
	non noble metal	copper	7440-50-8	815.335	40.37	40.42	403475	404000
wire	non noble metal	aluminium	7429-90-5	1.697	0.08	0.08	840	840
encapsulation	organic material	carbon black	1333-86-4	6.391	0.32		3163	
	inorganic material	antimonytrioxide	1309-64-4	13.364	0.66		6613	
	plastics	brominated resin	-	15.107	0.75		7476	
	plastics	epoxy resin	-	110.395	5.46		54630	
	inorganic material	silicondioxide	60676-86-0	435.770	21.56	28.75	215646	287528
leadfinish	non noble metal	tin	7440-31-5	21.462	1.06	1.06	10621	10621
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	121	122
solder	non noble metal	tin	7440-31-5	0.081			40	
	noble metal	silver	7440-22-4	0.101			50	
	non noble metal	lead	7439-92-1	3.844	0.19	0.19	1902	1992
glue	plastics	Polyimide	26023-21-2	0.157	0.01	0.01	77	77
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		88	
	non noble metal	iron	7439-89-6	0.590	0.03		292	
	non noble metal	copper	7440-50-8	589.466	29.17	29.21	291704	292084
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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